

- **Three Differential Transceivers in One Package**
- **Signaling Rates† Up to 30 Mbps**
- **Low Power and High Speed**
- **Designed for TIA/EIA-485, TIA/EIA-422, ISO 8482, and ANSI X3.277 (HVD SCSI Fast-20) Applications**
- **Common-Mode Bus Voltage Range -7 V to 12 V**
- **ESD Protection on Bus Terminals Exceeds 12 kV**
- **Driver Output Current up to ±60 mA**
- **Thermal Shutdown Protection**
- **Driver Positive and Negative Current Limiting**
- **Power-Up, Power-Down Glitch-Free Operation**
- **Pin-Compatible With the SN75ALS170**
- **Available in Shrink Small-Outline Package**

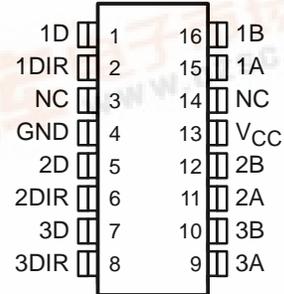
description

The SN65LBC170 and SN75LBC170 are monolithic integrated circuits designed for bidirectional data communication on multipoint bus-transmission lines. Potential applications include serial or parallel data transmission, cabled peripheral buses with twin axial, ribbon, or twisted-pair cabling. These devices are suitable for FAST-20 SCSI and can transmit or receive data pulses as short as 25 ns, with skew less than 3 ns.

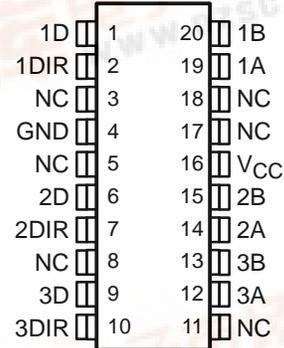
These devices combine three 3-state differential line drivers and three differential input line receivers, all of which operate from a single 5-V power supply.

The driver differential outputs and the receiver differential inputs are connected internally to form three differential input/output (I/O) bus ports that are designed to offer minimum loading to the bus whenever the driver is disabled or $V_{CC} = 0$. These ports feature a wide common-mode voltage range making the device suitable for party-line applications over long cable runs.

SN65LBC170DB (marked as BL170)
SN75LBC170DB (marked as BL170)
(TOP VIEW)

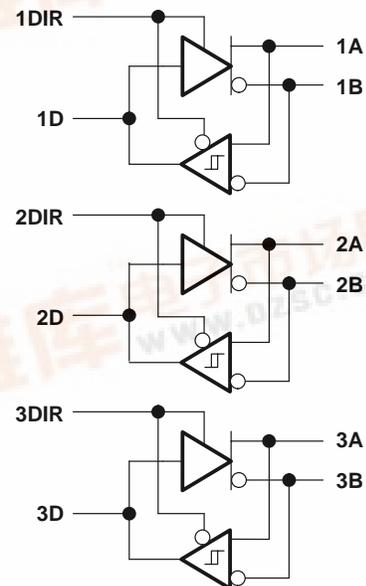


SN65LBC170DW (marked as 65LBC170)
SN75LBC170DW (marked as 75LBC170)
(TOP VIEW)



NC – No internal connection

logic diagram



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

† The signaling rate of a line is the number of voltage transitions that are made per second expressed in the units bps (bits per second).

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



SN65LBC170, SN75LBC170 TRIPLE DIFFERENTIAL TRANSCEIVERS

SLLS459B – NOVEMBER 2000 – REVISED FEBRUARY 2002

description (continued)

The driver's active-high enable and the receiver's active-low enable are tied together internally and provide a direction input for each driver/receiver pair.

The SN75LBC170 is characterized for operation over the temperature range of 0°C to 70°C. The SN65LBC170 is characterized for operation over the temperature range of -40°C to 85°C.

AVAILABLE OPTIONST†

T _A	PACKAGE	
	PLASTIC SHRINK SMALL-OUTLINE (JEDEC MO-150)	PLASTIC SMALL-OUTLINE (JEDEC MS-013)
0°C to 70°C	SN75LBC170DB	SN75LBC170DW
-40°C to 85°C	SN65LBC170DB	SN65LBC170DW

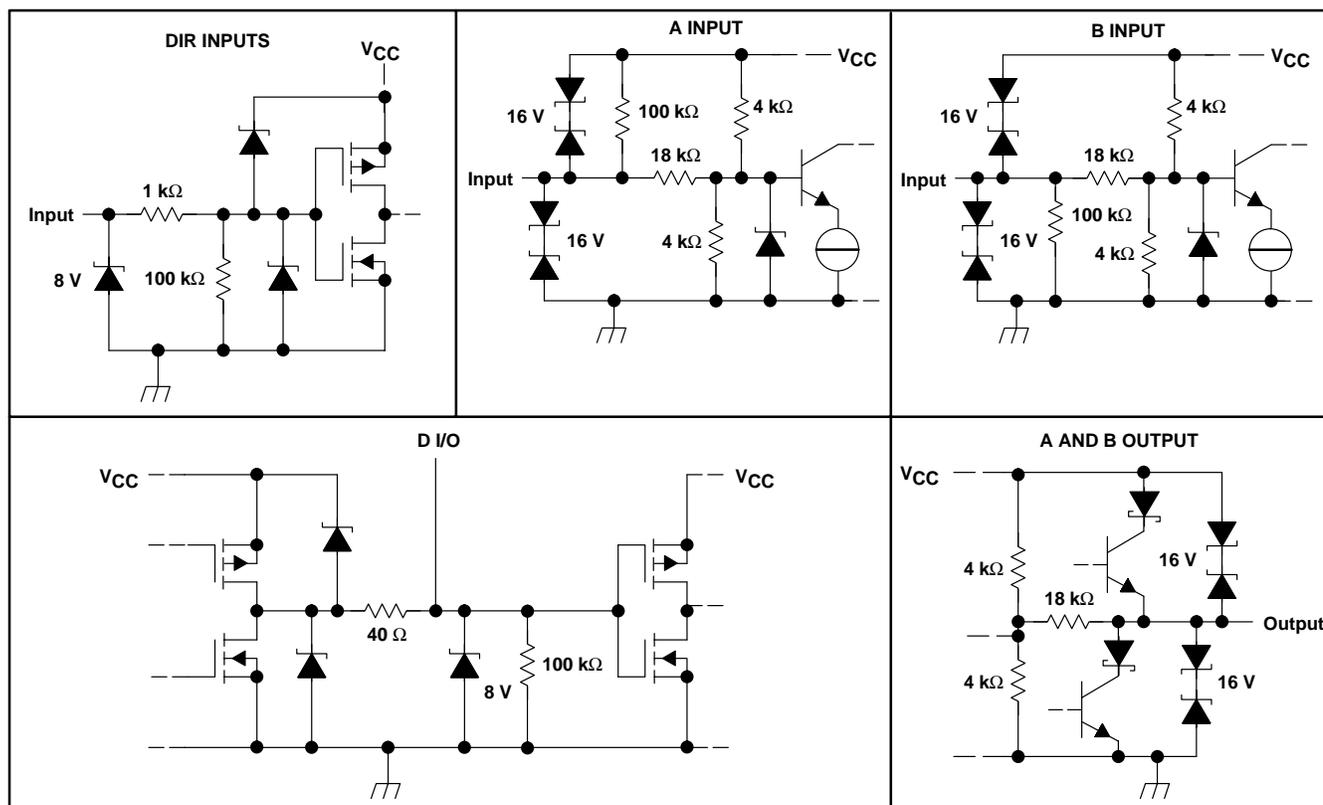
† Add R suffix for taped and reel

Function Tables

EACH DRIVER			EACH RECEIVER			
INPUT D	ENABLE DIR	OUTPUTS		DIFFERENTIAL INPUT (V _A -V _B)	ENABLE DIR	OUTPUT D
		A	B			
H	H	H	L	V _{ID} ≥ 0.2 V	L	H
L	H	L	H	-0.2 V < V _{ID} < 0.2 V	L	?
OPEN	H	L	H	V _{ID} ≤ -0.2 V	L	L
X	L	Z	Z	X	H	Z
X	OPEN	X	X	OPEN	L	H

H = high level, L = low level, X = irrelevant, Z = high impedance (off), ? = indeterminate

equivalent input and output schematic diagrams



SN65LBC170, SN75LBC170 TRIPLE DIFFERENTIAL TRANSCEIVERS

SLLS459B – NOVEMBER 2000 – REVISED FEBRUARY 2002

absolute maximum ratings†

Supply voltage, V_{CC} (see Note 1)	–0.3 V to 6 V
Voltage range at any bus I/O terminal (steady state)	–10 V to 15 V
Voltage input range, A and B, (transient pulse through 100 Ω , see Figure 12)	–30 V to 30 V
Voltage range at any D or DIR terminal	–0.5 V to $V_{CC} + 0.5$ V
Electrostatic discharge: Human body model (A, B, GND) (see Note 2)	12 kV
All pins	5 kV
Charged-device model (all pins) (see Note 3)	1 kV
Continuous total power dissipation	See Power Dissipation Rating Table
Storage temperature range, T_{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.
 2. Tested in accordance with JEDEC Standard 22, Test Method A114–A.
 3. Tested in accordance with JEDEC Standard 22, Test Method C101.

POWER DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$	DERATING FACTOR‡	$T_A = 70^\circ\text{C}$	$T_A = 85^\circ\text{C}$
	POWER RATING	ABOVE $T_A = 25^\circ\text{C}$	POWER RATING	POWER RATING
DB	995 mW	8.0 mW/°C	635 mW	515 mW
DW	1480 mW	11.8 mW/°C	950 mW	770 mW

‡ This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}		4.75	5	5.25	V
Voltage at any bus I/O terminal	A, B	–7		12	V
High-level input voltage, V_{IH}	D, DIR	2		V_{CC}	V
Low-level input voltage, V_{IL}		0		0.8	
Differential input voltage, V_{ID}	A with respect to B	–12		12	V
Output current	Driver	–60		60	mA
	Receiver	–8		8	
Operating free-air temperature, T_A	SN75LBC170	0		70	°C
	SN65LBC170	–40		85	

SN65LBC170, SN75LBC170 TRIPLE DIFFERENTIAL TRANSCEIVERS

SLLS459B – NOVEMBER 2000 – REVISED FEBRUARY 2002

DRIVER SECTION

electrical characteristics over recommended operating conditions

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{IK}	Input clamp voltage	D and DIR I _I = 18 mA	-1.5	-0.7		V
V _O	Open-circuit output voltage (single-ended)	A or B, No load	0		V _{CC}	V
V _{OD(SS)}	Steady-state differential output voltage magnitude‡	No load	3.8	4.3	V _{CC}	V
		R _L = 54 Ω, See Figure 1	1	1.6	2.4	
		With common-mode loading, See Figure 2	1	1.6	2.4	
ΔV _{OD}	Change in differential output voltage magnitude, V _{OD(H)} - V _{OD(L)}	R _L = 54 Ω, C _L = 50 pF See Figure 1	-0.2		0.2	V
V _{OC(SS)}	Steady-state common-mode output voltage		2	2.4	2.8	
ΔV _{OC(SS)}	Change in steady-state common-mode output voltage (V _{OC(H)} - V _{OC(L)})		-0.2		0.2	
I _I	Input current	D, DIR	-100		100	μA
I _O	Output current with power off	V _{CC} = 0 V, V _O = -7 V to 12 V	-700		900	μA
I _{OS}	Short-circuit output current	V _O = -7 V to 12 V, See Figure 7	-250		250	mA
I _{CC}	Supply current (driver enabled)	D at 0 V or V _{CC} , DIR at V _{CC} , No load		14	20	mA

† All typical values are at V_{CC} = 5 V and T_A = 25°C.

‡ The minimum V_{OD} may not fully comply with TIA/EIA-485-A at operating temperatures below 0°C. System designers should take the possibly lower output signal into account in determining the maximum signal-transmission distance.

switching characteristics over recommended operating conditions

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	Differential output propagation delay, low-to-high	R _L = 54 Ω, C _L = 50 pF, See Figure 3	4	8.5	12	ns
t _{PHL}	Differential output propagation delay, high-to-low		4	8.5	11	
t _r	Differential output rise time		3	7.5	11	
t _f	Differential output fall time		3	7.5	11	
t _{sk(p)}	Pulse skew (t _{PLH} - t _{PHL})				2	
t _{sk(o)}	Output skew§				1.5	
t _{sk(pp)}	Part-to-part skew¶				2	
t _{PLH}	Differential output propagation delay, low-to-high		See Figure 4, (HVD SCSI double-terminated load)	3	7	
t _{PHL}	Differential output propagation delay, high-to-low	3		7.5	10	
t _r	Differential output rise time	3		7.5	12	
t _f	Differential output fall time	3		7.5	12	
t _{sk(p)}	Pulse skew (t _{PLH} - t _{PHL})				3	
t _{sk(o)}	Output skew§				1.5	
t _{sk(pp)}	Part-to-part skew¶				2.5	
t _{PZH}	Output enable time to high level	See Figure 5			15	25
t _{PHZ}	Output disable time from high level			18	25	
t _{PZL}	Output enable time to low level	See Figure 6		10	25	ns
t _{PLZ}	Output disable time from low level			17	25	

§ Output skew (t_{sk(o)}) is the magnitude of the time delay difference between the outputs of a single device with all of the inputs connected together.

¶ Part-to-part skew (t_{sk(pp)}) is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same input signals, the same supply voltages, at the same temperature, and have identical packages and test circuits.

SN65LBC170, SN75LBC170 TRIPLE DIFFERENTIAL TRANSCEIVERS

SLLS459B – NOVEMBER 2000 – REVISED FEBRUARY 2002

RECEIVER SECTION

electrical characteristics over recommended operating conditions

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{IT+}	Positive-going differential input voltage threshold	See Figure 8			0.2	V
V_{IT-}	Negative-going differential input voltage threshold		-0.2			
V_{hys}	Hysteresis voltage ($V_{IT+} - V_{IT-}$)			40		mV
V_{OH}	High-level output voltage	$V_{ID} = 200$ mV, $I_{OH} = -8$ mA, See Figure 8	4	4.7	V_{CC}	V
V_{OL}	Low-level output voltage	$V_{ID} = -200$ mV, $I_{OL} = -8$ mA, See Figure 8	0	0.2	0.4	
I_I	Line input current	Other input = 0 V			0.9	mA
					-0.7	
R_I	Input resistance	A, B	12			k Ω
I_{CC}	Supply current (receiver enabled)	A, B, D, and DIR open			16	mA

† All typical values are at $V_{CC} = 5$ V and $T_A = 25^\circ\text{C}$.

switching characteristics over recommended operating conditions

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high level output	See Figure 9	7		16	ns
t_{PHL}	Propagation delay time, high-to-low level output		7		16	
t_r	Receiver output rise time			1.3	3	ns
t_f	Receiver output fall time			1.3	3	
t_{PZH}	Receiver output enable time to high level	See Figure 10		26	40	ns
t_{PHZ}	Receiver output disable time from high level				40	
t_{PZL}	Receiver output enable time to low level	See Figure 11		29	40	ns
t_{PLZ}	Receiver output enable time to high level				40	
$t_{sk(p)}$	Pulse skew ($ t_{PLH} - t_{PHL} $)				2	ns
$t_{sk(o)}$	Output skew‡				1.5	ns
$t_{sk(pp)}$	Part-to-part skew§				3	ns

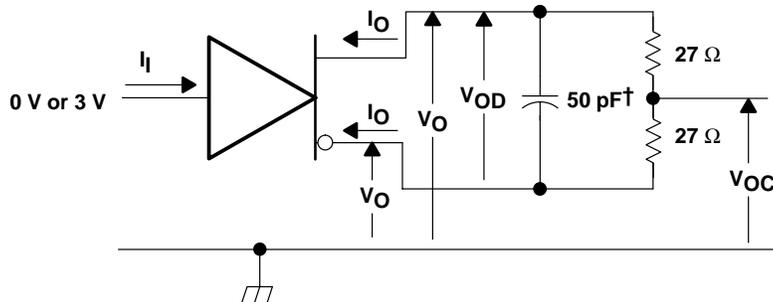
‡ Output skew ($t_{sk(o)}$) is the magnitude of the time delay difference between the outputs of a single device with all of the inputs connected together.

§ Part-to-part skew ($t_{sk(pp)}$) is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same input signals, the same supply voltages, at the same temperature, and have identical packages and test circuits.

SN65LBC170, SN75LBC170 TRIPLE DIFFERENTIAL TRANSCEIVERS

SLLS459B – NOVEMBER 2000 – REVISED FEBRUARY 2002

PARAMETER MEASUREMENT INFORMATION



† Includes probe and jig capacitance

Figure 1. Driver Test Circuit, V_{OD} and V_{OC} Without Common-Mode Loading

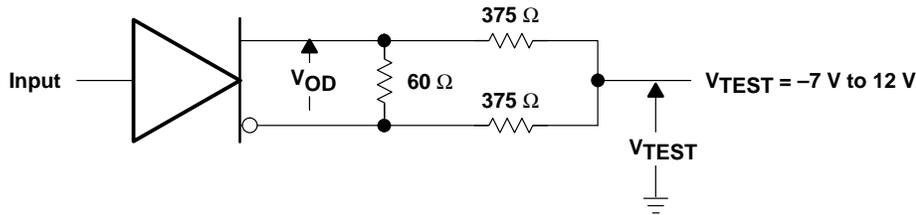
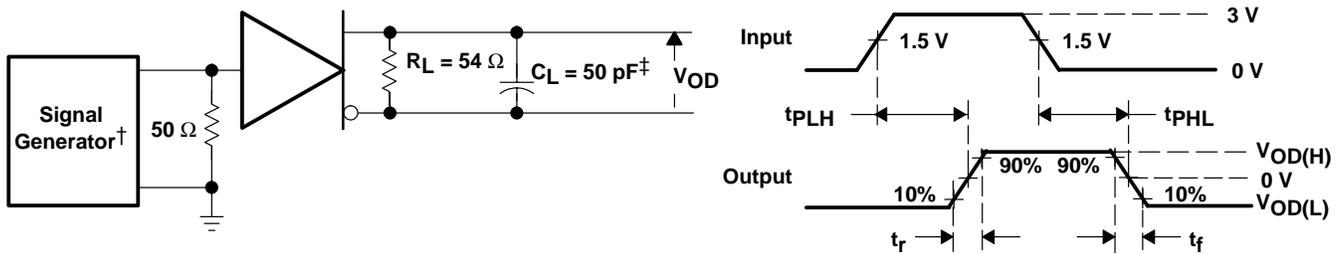


Figure 2. Driver Test Circuit, V_{OD} With Common-Mode Loading



† PRR = 1 MHz, 50% Duty Cycle, $t_r < 6$ ns, $t_f < 6$ ns, $Z_0 = 50 \Omega$

‡ Includes probe and jig capacitance

Figure 3. Driver Switching Test Circuit and Waveforms, 485-Loading

SN65LBC170, SN75LBC170 TRIPLE DIFFERENTIAL TRANSCEIVERS

SLLS459B – NOVEMBER 2000 – REVISED FEBRUARY 2002

PARAMETER MEASUREMENT INFORMATION

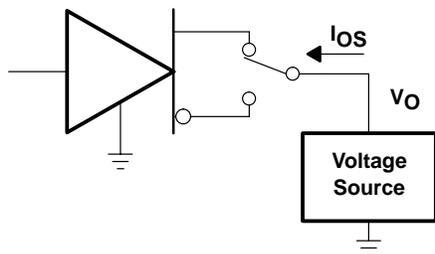


Figure 7. Driver Short-Circuit Test

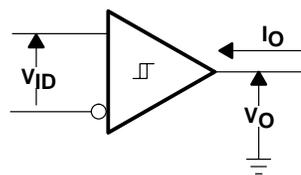
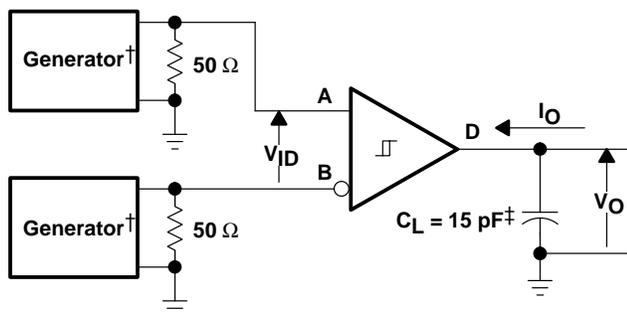
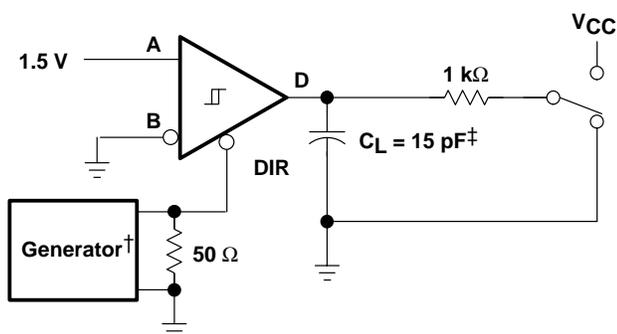


Figure 8. Receiver DC Parameters



† PRR = 1 MHz, 50% Duty Cycle, $t_r < 6$ ns, $t_f < 6$ ns, $Z_0 = 50 \Omega$
‡ Includes probe and jig capacitance

Figure 9. Receiver Switching Test Circuit and Waveforms



† PRR = 1 MHz, 50% Duty Cycle, $t_r < 6$ ns, $t_f < 6$ ns, $Z_0 = 50 \Omega$
‡ Includes probe and jig capacitance

Figure 10. Receiver Enable/Disable Test, High Output

SN65LBC170, SN75LBC170 TRIPLE DIFFERENTIAL TRANSCEIVERS

SLLS459B – NOVEMBER 2000 – REVISED FEBRUARY 2002

PARAMETER MEASUREMENT INFORMATION

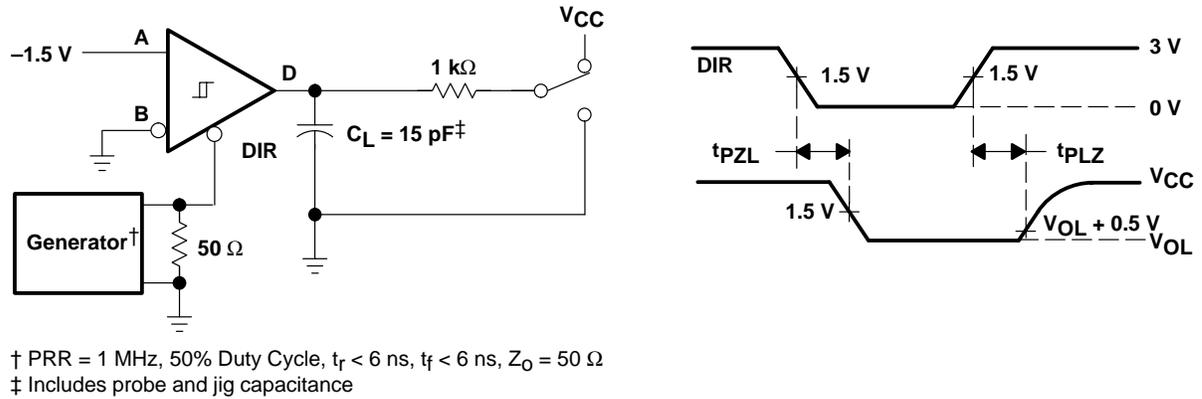


Figure 11. Receiver Enable/Disable Test, Low Output

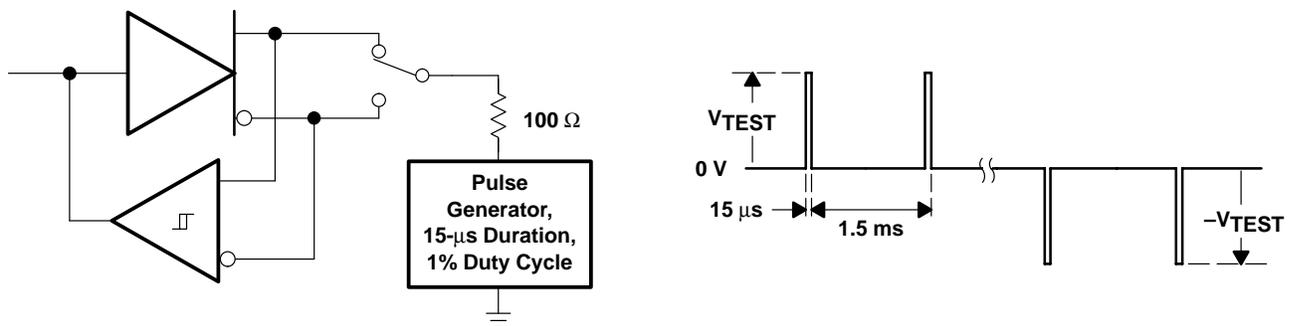


Figure 12. Test Circuit and Waveform, Transient Over Voltage Test

SN65LBC170, SN75LBC170 TRIPLE DIFFERENTIAL TRANSCEIVERS

SLLS459B – NOVEMBER 2000 – REVISED FEBRUARY 2002

TYPICAL CHARACTERISTICS

DIFFERENTIAL OUTPUT VOLTAGE
vs
OUTPUT CURRENT

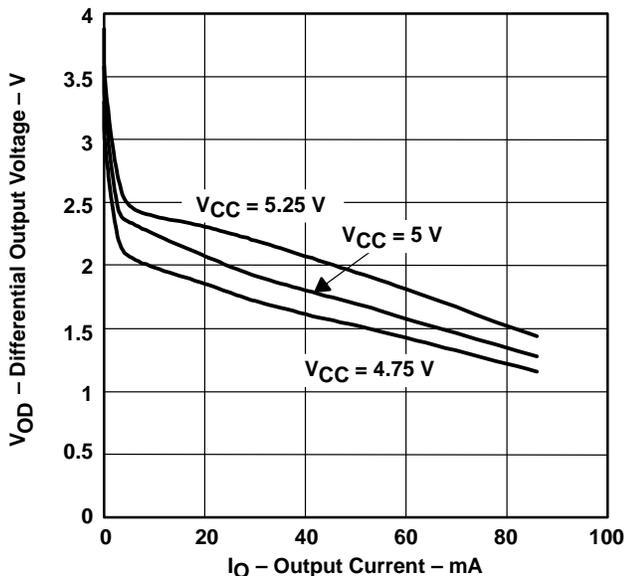


Figure 13

DIFFERENTIAL OUTPUT VOLTAGE
vs
FREE-AIR TEMPERATURE

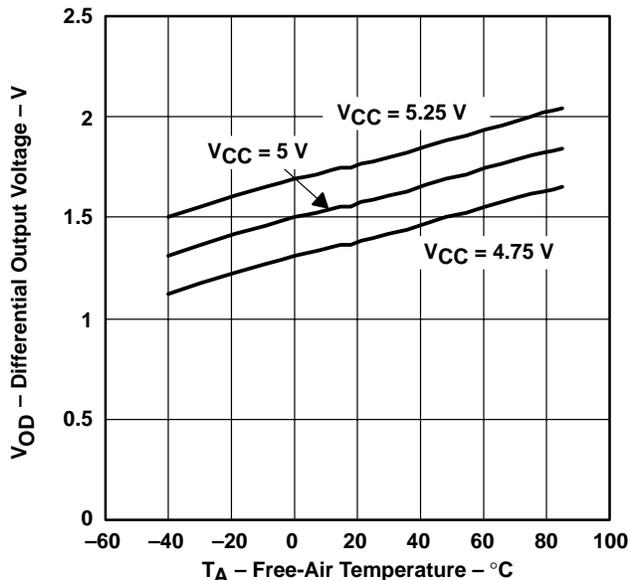


Figure 14

DRIVER PROPAGATION DELAY
vs
FREE-AIR TEMPERATURE

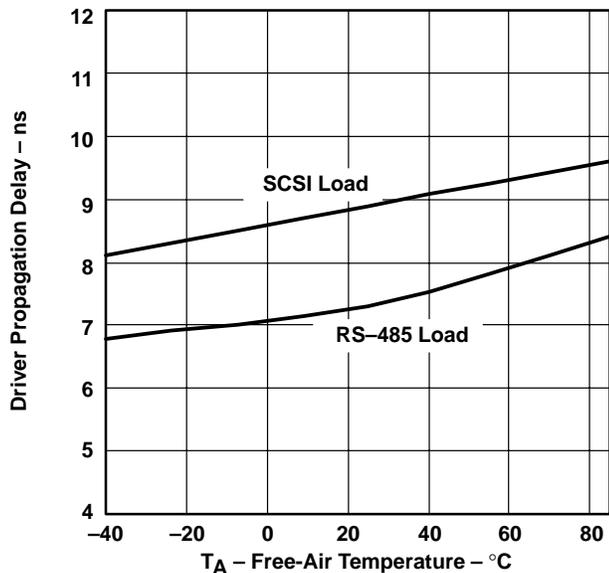


Figure 15

SUPPLY CURRENT
vs
SIGNALING RATE

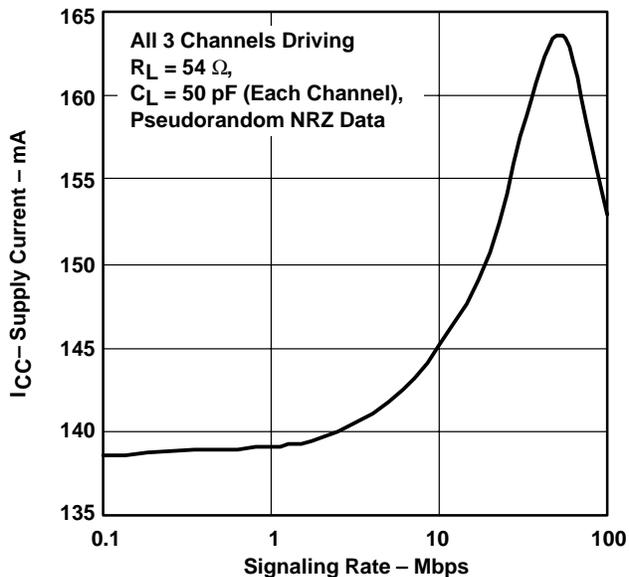


Figure 16

SN65LBC170, SN75LBC170 TRIPLE DIFFERENTIAL TRANSCEIVERS

SLLS459B – NOVEMBER 2000 – REVISED FEBRUARY 2002

TYPICAL CHARACTERISTICS

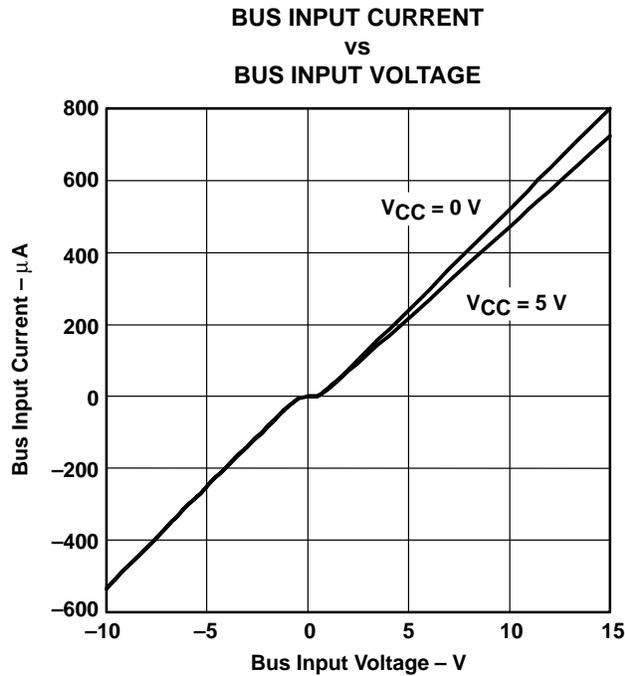


Figure 17

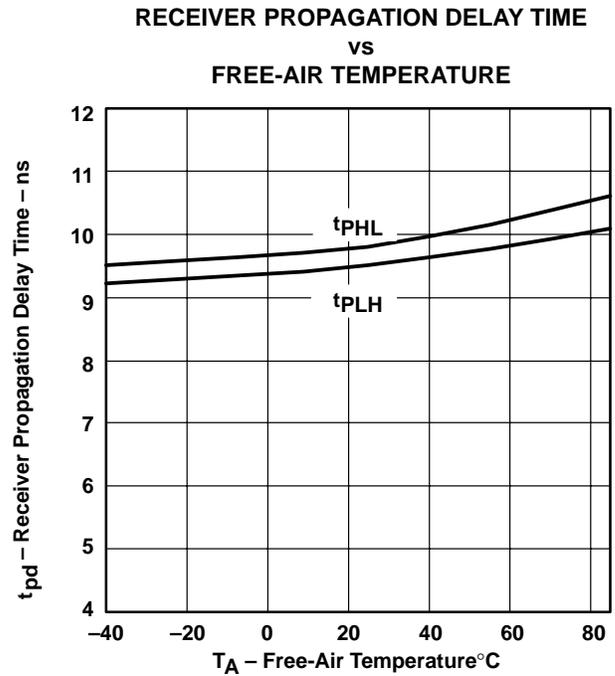


Figure 18

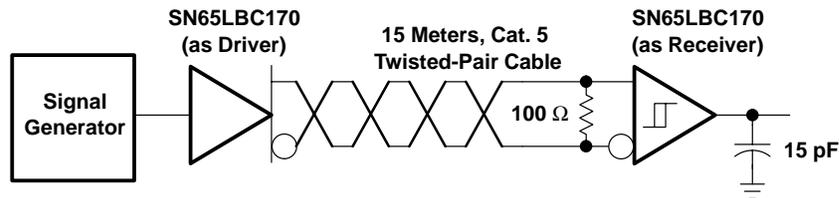


Figure 19. Circuit Diagram for Signaling Characteristics

SN65LBC170, SN75LBC170 TRIPLE DIFFERENTIAL TRANSCEIVERS

SLLS459B – NOVEMBER 2000 – REVISED FEBRUARY 2002

TYPICAL CHARACTERISTICS

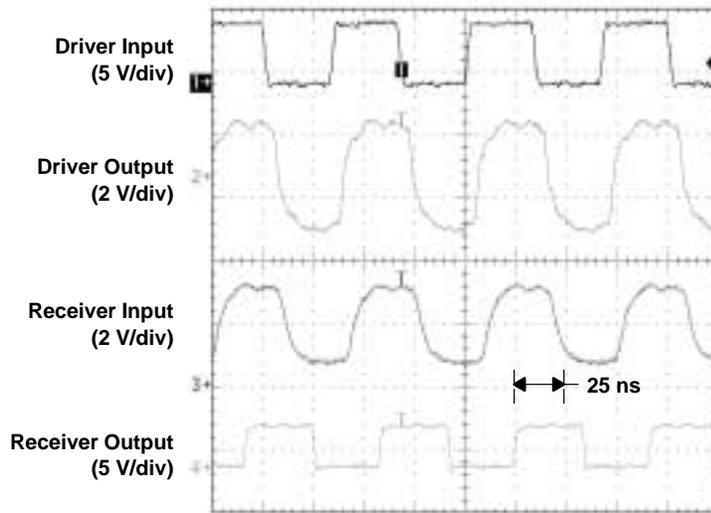


Figure 20. Signal Waveforms at 30 Mbps

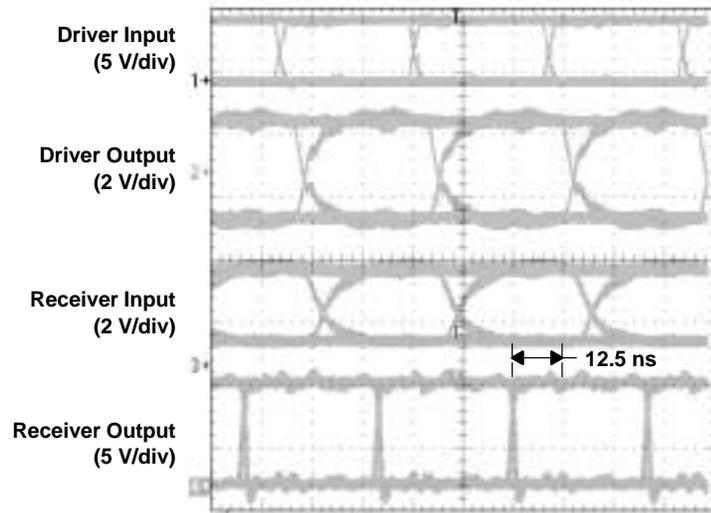


Figure 21. Eye Patterns, Pseudorandom Data at 30 Mbps

SN65LBC170, SN75LBC170 TRIPLE DIFFERENTIAL TRANSCEIVERS

SLLS459B – NOVEMBER 2000 – REVISED FEBRUARY 2002

TYPICAL CHARACTERISTICS

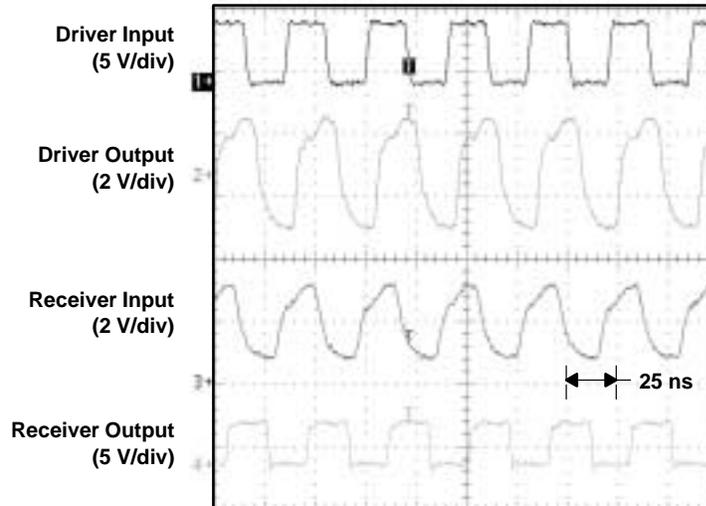


Figure 22. Signal Waveforms at 50 Mbps

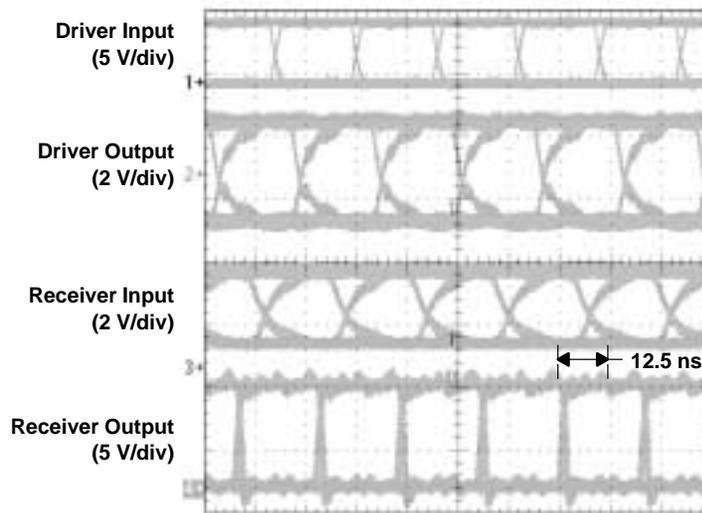


Figure 23. Eye Patterns, Pseudorandom Data at 50 Mbps

SN65LBC170, SN75LBC170 TRIPLE DIFFERENTIAL TRANSCEIVERS

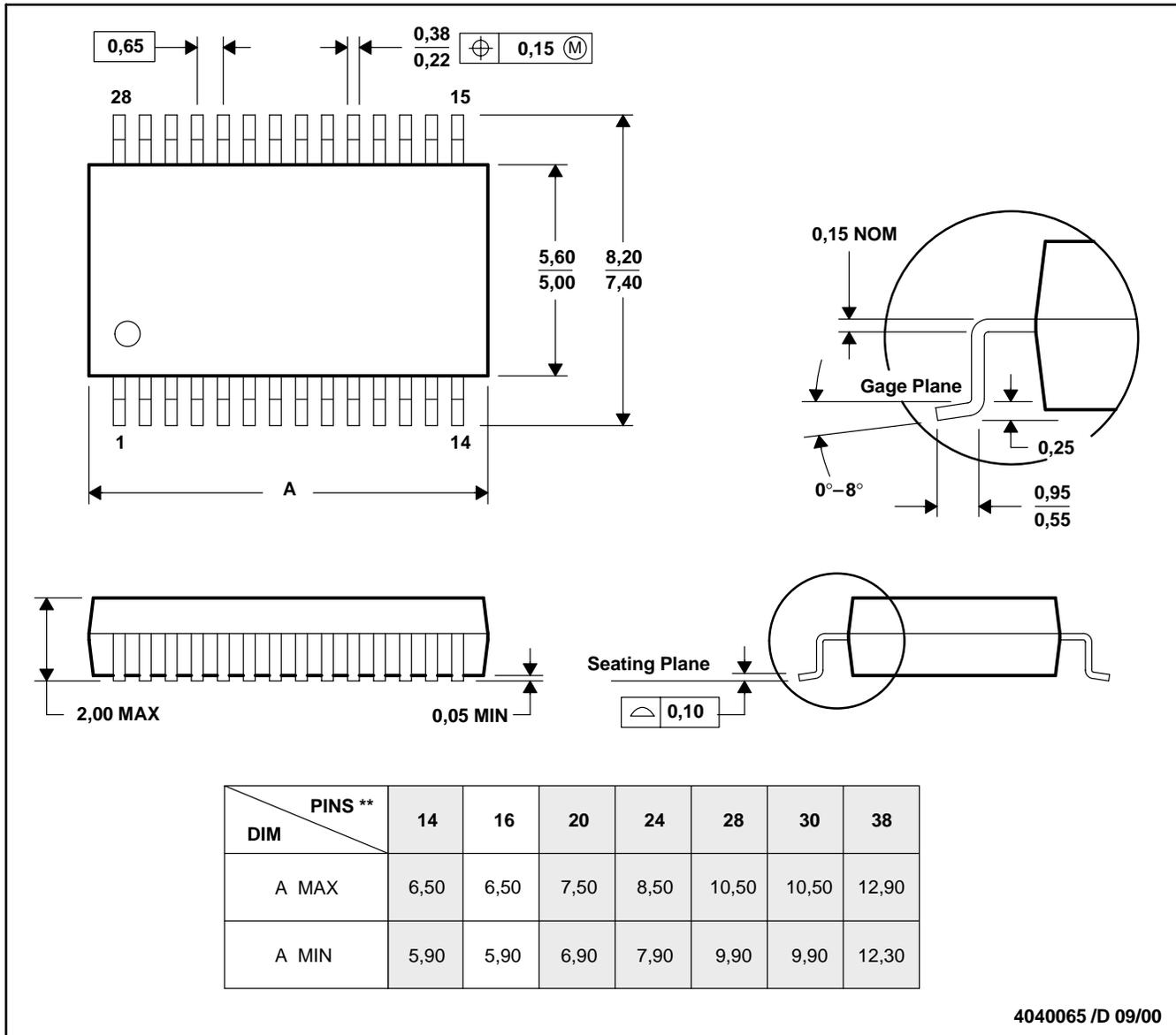
SLLS459B – NOVEMBER 2000 – REVISED FEBRUARY 2002

MECHANICAL DATA

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

SN65LBC170, SN75LBC170 TRIPLE DIFFERENTIAL TRANSCEIVERS

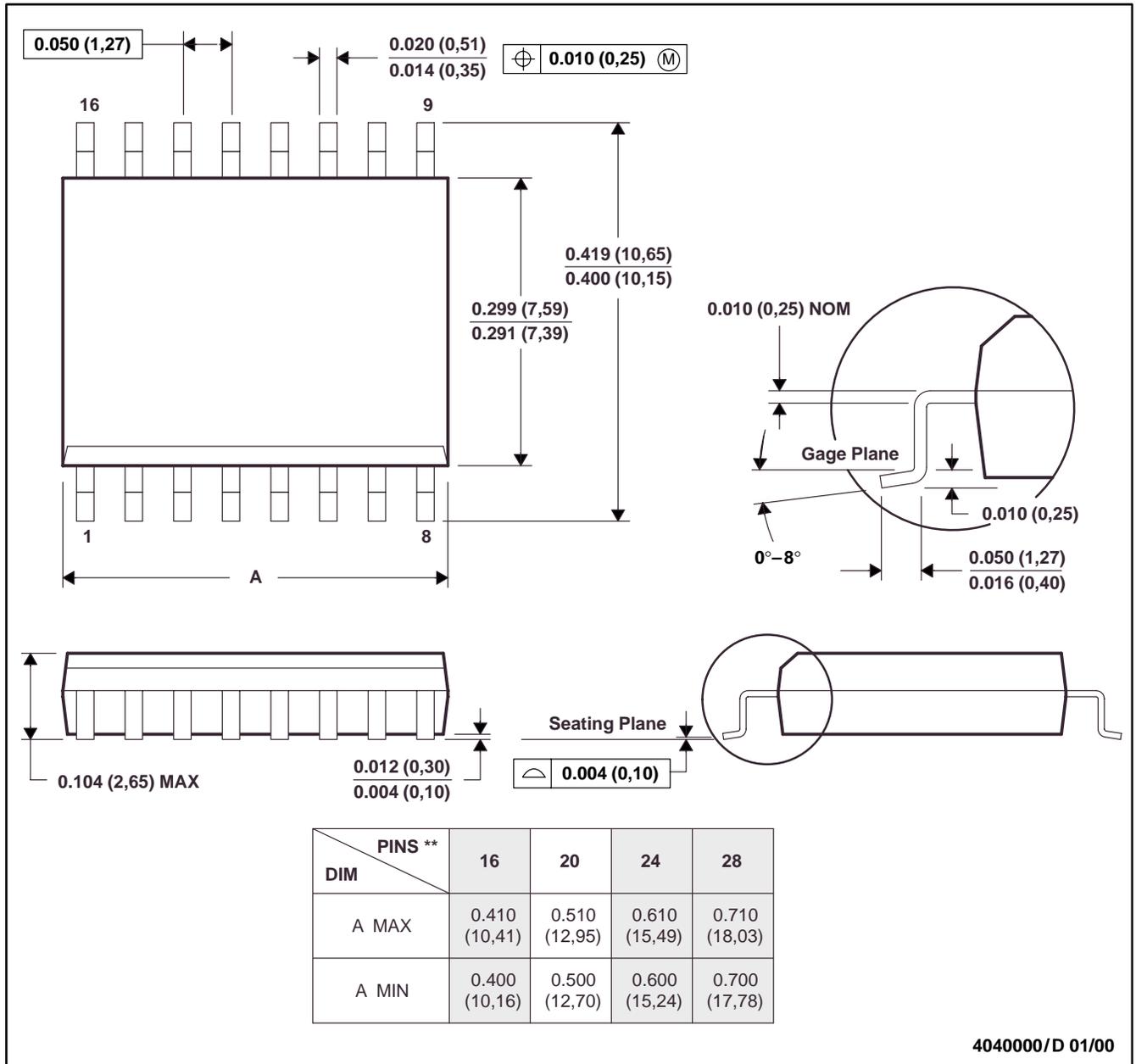
SLLS459B – NOVEMBER 2000 – REVISED FEBRUARY 2002

MECHANICAL DATA

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MS-013

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN65LBC170DB	ACTIVE	SSOP	DB	16	80	None	CU NIPDAU	Level-1-220C-UNLIM
SN65LBC170DBR	ACTIVE	SSOP	DB	16	2000	None	CU NIPDAU	Level-1-220C-UNLIM
SN65LBC170DW	ACTIVE	SOIC	DW	20	25	None	CU NIPDAU	Level-1-220C-UNLIM
SN65LBC170DWR	ACTIVE	SOIC	DW	20	2500	None	CU NIPDAU	Level-1-220C-UNLIM
SN75LBC170DB	ACTIVE	SSOP	DB	16	80	None	CU NIPDAU	Level-1-220C-UNLIM
SN75LBC170DBR	ACTIVE	SSOP	DB	16	2000	None	CU NIPDAU	Level-1-220C-UNLIM
SN75LBC170DBRG4	PREVIEW	SSOP	DB	16	2000	None	Call TI	Call TI
SN75LBC170DW	ACTIVE	SOIC	DW	20	50	None	CU NIPDAU	Level-1-220C-UNLIM
SN75LBC170DWR	ACTIVE	SOIC	DW	20	2500	None	CU NIPDAU	Level-1-220C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265